BONDING THE STARS







Thin Wire Wedge-Wedge Bonder 5630

Bond System

Wire types Aluminium and gold wire 17,5–75µm on 2" spool

Bondhead Wedge-Wedge for thin wire

Standard tool 16mm (optionally 19mm) Standard wedges of 1" length, 45° wire feed

Motorized wire spool (optional)

Ultrasonic F&S Go System (option

F&S Generator 100 kHz (optional 65, 140kHz)

Bonder Base

Axes

- Working area X/Y-axis 100x100mm Z-axis 60mm
- Step resolution 0,25μm
- Repeatability < 2µm

Hardware

- Dual Core PC, 1,6 GHz processor,
- 4 GB RAM, Ethernet, 4x USB-Hub Front
- Firewire CCD colour camera 1,4 MPixel
- Network-capable with TCP / IP server

Software

- Single bonds up to complex programs,
- Loop shapes can be saved in libraries
- Optional pattern recognition

Speed 20 wires per minute

Dimenstions W x D x H - 70 x 65x 70 cm, weight approx. 80kg

Connections 100-240 VAC, 1 Phase, 50/60 Hz, max 500 VA

Ø 6mm standard vacuum tubing

Heater controller Integrated in the machine 0-250C°

Die 56xx Series:

The semi-automatic Wedge-Wedge Bonder 5630 fills the gap between the manual Wedge to the automatic-bonder. He is on basis 5600-series fully PC controlled and allows any number of bonds to be programmed.

Pre-programmed adjust points are targeted through the camera's cross hair targeting system and the programmed bonds are executed automatically.

Two operating modes are available: Single bond for repair of various bond samples and making single bonds (manualautomatic) and multi wire for teaching and bonding chips or various bond samples (semi & fully automatic).

The 5630 can also be used as Gold Wire or Alu Heavy Wire as well as pull-/shear tester by simply replacing the bond head and loading the appropriate software.

Set up time: ~3 minutes.
Ask us for more information!

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Workholder

Standard-Workholder for parts up to 4x4" with Vacuum und mechanical clamping



Optional:



workholders up to 4x4" with jaws



TO workhoder with mechanical clamping



4x4" workholder with . rubberized surface and mechanical clamping

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